



Spectra7 Product Named One Of The Most Innovative Solutions For Data Center Applications

Best of DesignCon 2017

PALO ALTO, CA - February 21, 2017 - (TSX:SEV) Spectra7 Microsystems Inc. ("Spectra7" or the "Company"), a leading provider of high-performance analog semiconductor products for virtual reality (VR), augmented reality (AR), data center and other connectivity markets shared today that its GaugeChanger Plus™ product line is listed as one of the "Best of DesignCon 2017."

The Company debuted its GaugeChanger Plus™ technology earlier this month at DesignCon 2017 at the Santa Clara Convention Center. More than 160 major companies showcased their products relating to signal integrity and high-speed applications, but only a distinct few were named in the article published by Connector and Cable Assembly Supplier at ConnectorSupplier.com.

"I'm delighted and honored by this recognition of our market-leading innovative data center technology," said Spectra7 CEO, Raouf Halim.

The article described Spectra7's GaugeChanger Plus™ product line as "one of the most innovative solutions to solving the problem of bulky copper cables," and further described the technology by stating that, "this 'smart' copper cable approach is a cost effective alternative to expensive fiber optic or active copper cables."

The article also described several industry trends the author noticed after attending DesignCon 2017, and the impression the show left with him, including, "Those that predicted the inability of copper conductors to support the ever-increasing demands for higher speeds will continue to be frustrated."

To read the full article visit: <http://www.connectorsupplier.com/designcon-2017/>

ABOUT SPECTRA7 MICROSYSTEMS INC.

Spectra7 Microsystems Inc. is a high performance analog semiconductor company delivering unprecedented bandwidth, speed and resolution to enable disruptive industrial design for leading electronics manufacturers in virtual reality, augmented reality, data centers and other connectivity markets. Spectra7 is based in Palo Alto, California with design centers in Markham, Ontario, Cork, Ireland, and Little Rock, Arkansas. For more information, please visit www.spectra7.com.

ABOUT DESIGNCON

DesignCon is the world's premier conference for chip, board, and systems design



engineers in the high-speed communications and semiconductor communities. DesignCon, created by engineers for engineers, takes place annually in Silicon Valley

and remains the largest gathering of chip, board, and systems designers in the country. This three-day technical conference and expo combines technical paper sessions, tutorials, industry panels, product demos and exhibits from the industry's leading experts and solutions providers. More information is available at: designcon.com. DesignCon is organized by UBM Americas, a part of UBM plc (UBM.L), an Events First marketing and communications services business. For more information, visit ubmamericas.com.

CAUTIONARY NOTES

Certain statements contained in this press release constitute "forward-looking statements". All statements other than statements of historical fact contained in this press release, including, without limitation, those regarding the Company's future financial position and results of operations, strategy, proposed acquisitions, plans, objectives, goals and targets, and any statements preceded by, followed by or that include the words "believe", "expect", "aim", "intend", "plan", "continue", "will", "may", "would", "anticipate", "estimate", "forecast", "predict", "project", "seek", "should" or similar expressions or the negative thereof, are forward-looking statements. These statements are not historical facts but instead represent only the Company's expectations, estimates and projections regarding future events. These statements are not guarantees of future performance and involve assumptions, risks and uncertainties that are difficult to predict. Therefore, actual results may differ materially from what is expressed, implied or forecasted in such forward-looking statements. Additional factors that could cause actual results, performance or achievements to differ materially include, but are not limited to the risk factors discussed in the Company's annual MD&A for the year ended December 31, 2015 and the interim MD&A for the nine months ended September 30, 2016. Management provides forward-looking statements because it believes they provide useful information to investors when considering their investment objectives and cautions investors not to place undue reliance on forward-looking information. Consequently, all of the forward-looking statements made in this press release are qualified by these cautionary statements and other cautionary statements or factors contained herein, and there can be no assurance that the actual results or developments will be realized or, even if substantially realized, that they will have the expected consequences to, or effects on, the Company. These forward-looking statements are made as of the date of this press release and the Company assumes no obligation to update or revise them to reflect subsequent information, events or circumstances or otherwise, except as required by law.

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